



CSG25H2500

Gate Turn-off Thyristor

High-end Power Semiconductor Manufacturer

**FEATURES**

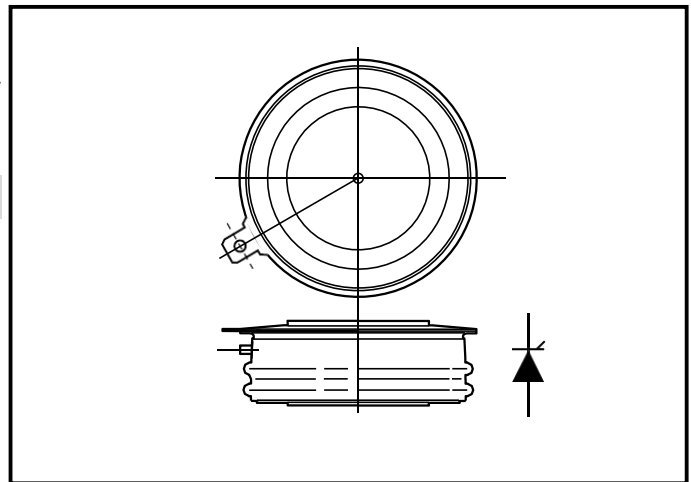
- Double Side Cooling
- High Voltage Capability
- Fault Protection Without Fuses
- High Surge Current Capability
- Turn-off Capability Allows Reduction in Equipment Size and Weight. Low Noise Emission Reduces Acoustic Cladding Necessary

**KEY PARAMETERS**

$V_{DRM}$	2500V
$I_{T(AV)}$	865A
$I_{TCM}$	2500A
$dV_D/dt$	1000V/ $\mu$ s
$dI_T/dt$	300A/ $\mu$ s

**APPLICATIONS**

- Variable speed AC motor drive inverters (VSD-AC)
- High Voltage Converters
- Choppers
- DC/DC Converters



Outline type code: H.  
See Package Details for further information

**VOLTAGE RATINGS**

Type Number	Repetitive Peak Off-state Voltage $V_{DRM}$ (V)	Repetitive Peak Reverse Voltage $V_{RRM}$ (V)	Conditions
CSG25H2500	2500	17	$T_{vj} = 125^{\circ}C, I_{DM} = 50mA, I_{RRM} = 50mA$

**CURRENT RATINGS**

Symbol	Parameter	Condition	Max.	Units
$I_{TCM}$	Repetitive peak controllable on-state current	$V_D = V_{DRM}, T_j = 125^{\circ}C, dI_{GQ}/dt = 40A/s, C_S = 6.0 F$	2500	A
$I_{T(AV)}$	Mean on-state current	$T_{HS} = 80^{\circ}C, Double\ side\ cooled. Half\ sine\ 50Hz$	865	A
$I_{T(RMS)}$	RMS on-state current	$T_{HS} = 80^{\circ}C, Double\ side\ cooled. Half\ sine\ 50Hz$	1360	A



## SURGE RATINGS

Symbol	Parameter	Test Conditions	Max.	Units
$I_{TSM}$	Surge (non repetitive) on-state current	10ms half sine. $T_j = 125^\circ\text{C}$	16.0	kA
$I^2t$	$I^2t$ for fusing	10ms half sine. $T_j = 125^\circ\text{C}$	1.40	MA <sup>2</sup> s
$di_T/dt$	Critical rate of rise of on-state current	$V_D = 1500\text{V}$ , $I_T = 2000\text{A}$ , $T_j = 125^\circ\text{C}$ , $I_{FG} > 30\text{A}$ , Rise time $> 1.0 \mu\text{s}$	300	A/ $\mu\text{s}$
$dV_D/dt$	Rate of rise of off-state voltage	To 66% $V_{DRM}$ ; $R_{GK} = 1.5 \Omega$ , $T_j = 125^\circ\text{C}$	135	V/ $\mu\text{s}$
		To 66% $V_{DRM}$ ; $V_{RG} = -2\text{V}$ , $T_j = 125^\circ\text{C}$	1000	V/ $\mu\text{s}$
$L_S$	Peak stray inductance in snubber circuit	$I_T = 2000\text{A}$ , $V_{DM} = 2500\text{V}$ , $T_j = 125^\circ\text{C}$ , $di_{GQ}/dt = 40\text{A}/\mu\text{s}$ , $C_S = 2.0 \mu\text{F}$	200	nH

## GATE RATINGS

Symbol	Parameter	Test Conditions	Min.	Max.	Units
$V_{RGM}$	Peak reverse gate voltage	This value may be exceeded during turn-off	-	16	V
$I_{FGM}$	Peak forward gate current		20	100	A
$P_{FG(AV)}$	Average forward gate power		-	15	W
$P_{RGM}$	Peak reverse gate power		-	19	kW
$di_{GQ}/dt$	Rate of rise of reverse gate current		30	60	A/ $\mu\text{s}$
$t_{ON(min)}$	Minimum permissible on time		50	-	$\mu\text{s}$
$t_{OFF(min)}$	Minimum permissible off time		100	-	$\mu\text{s}$

## THERMAL AND MECHANICAL RATINGS

Symbol	Parameter	Test Conditions		Min.	Max.	Units
$R_{th(j-hs)}$	Thermal resistance – junction to heatsink surface	Double side cooled	DC	-	0.018	$^\circ\text{C}/\text{W}$
		Single side cooled	Anode DC	-	0.03	$^\circ\text{C}/\text{W}$
			Cathode DC	-	0.045	$^\circ\text{C}/\text{W}$
$R_{th(c-hs)}$	Contact thermal resistance	Clamping force 20.0kN With mounting compound	Per contact	-	0.006	$^\circ\text{C}/\text{W}$
$T_{vj}$	Virtual junction temperature	On-state (conducting)		-	125	$^\circ\text{C}$
$T_{OP}/T_{stg}$	Operating junction/storage temperature range			-40	125	$^\circ\text{C}$
$F_m$	Clamping force			18.0	22.0	kN



**GTO CHARACTERISTICS**

$T_j = 125^\circ\text{C}$  unless stated otherwise

Symbol	Parameter	Test Conditions	Min	Max.	Units
$V_{TM}$	On-state voltage	At 2000A peak, $I_{G(ON)} = 7\text{A dc}$	-	2.6	V
$I_{DM}$	Peak off-state current	$V_{DRM} = 2500\text{V}$ , $V_{RG} = 0\text{V}$	-	100	mA
$I_{RRM}$	Peak reverse current	At $V_{RRM}$	-	50	mA
$V_{GT}$	Gate trigger voltage	$V_D = 24\text{V}$ , $I_T = 100\text{A}$ , $T_j = 25^\circ\text{C}$	-	1.0	V
$I_{GT}$	Gate trigger current	$V_D = 24\text{V}$ , $I_T = 100\text{A}$ , $T_j = 25^\circ\text{C}$	-	3.0	A
$I_{RGM}$	Reverse gate cathode current	$V_{RGM} = 16\text{V}$ , No gate/cathode resistor	-	50	mA
$E_{ON}$	Turn-on energy	$V_D = 1500\text{V}$ $I_T = 2000\text{A}$ , $di_T/dt = 300\text{A}/\mu\text{s}$ $I_{FG} = 30\text{A}$ , rise time $< 1.0 \mu\text{s}$	-	1188	mJ
$t_d$	Delay time		-	1.5	$\mu\text{s}$
$t_r$	Rise time		-	3.5	$\mu\text{s}$
$E_{OFF}$	Turn-off energy	$I_T = 2000\text{A}$ , $V_{DM} = 2500\text{V}$ , Snubber capacitor $C_s = 2.0 \mu\text{F}$ , $di_{GQ}/dt = 40\text{A}/\mu\text{s}$	-	4000	mJ
$t_{gs}$	Storage time		-	17.0	s
$t_{gf}$	Fall time		-	2.0	s
$t_{gq}$	Gate controlled turn-off time		-	19.0	s
$Q_{GQ}$	Turn-off gate charge		-	6600	C
$Q_{GQT}$	Total turn-off gate charge		-	13200	C
$I_{GQM}$	Peak reverse gate current		-	650	A



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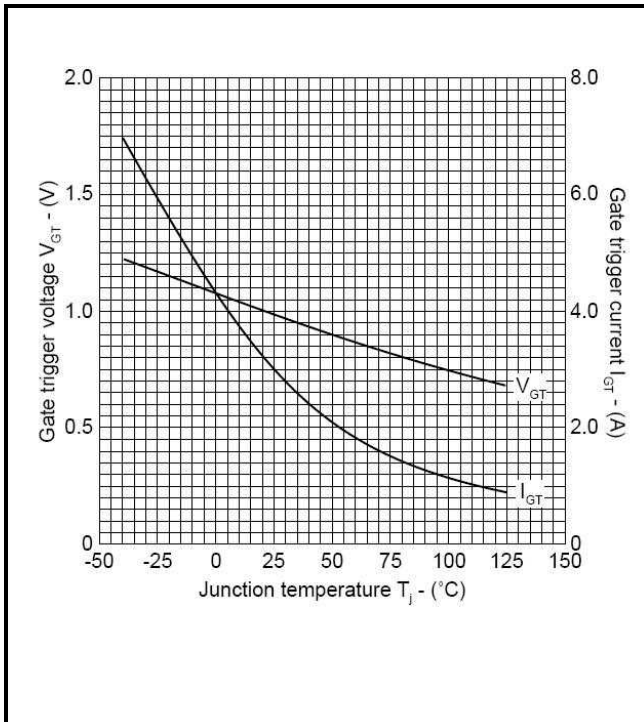


Fig.1 Maximum gate trigger voltage/current vs junction temperature

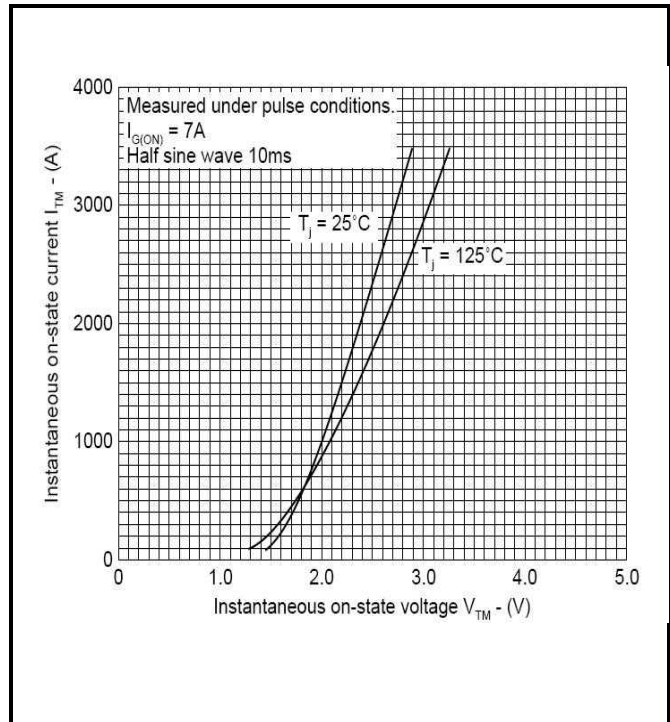


Fig.2 On-state characteristics

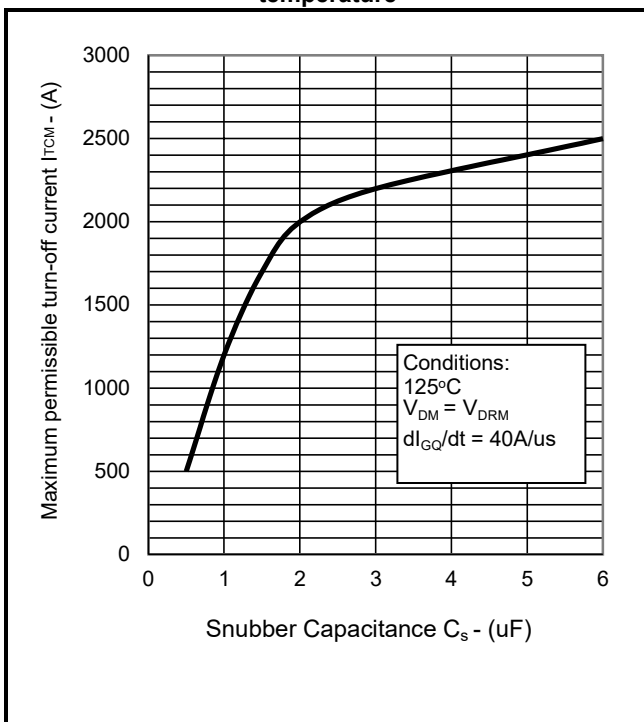


Fig.3 Maximum dependence of  $I_{TCM}$  on  $C_s$

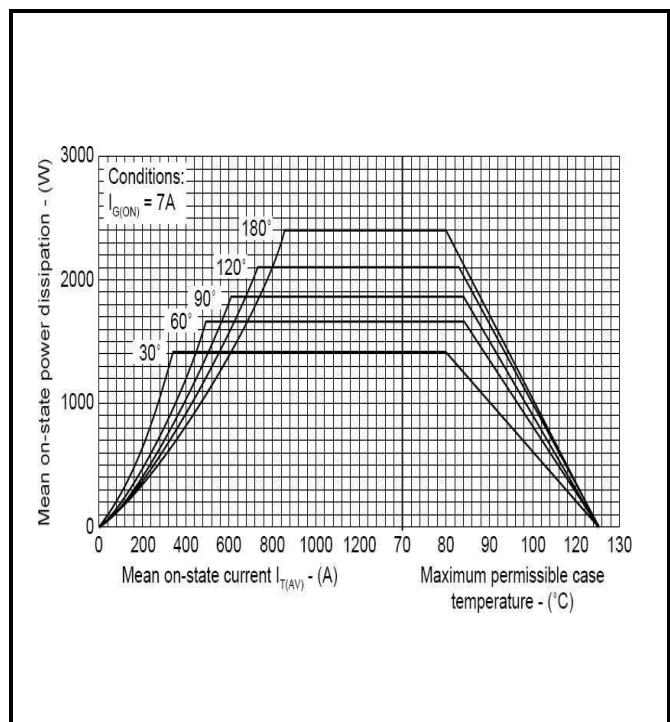


Fig.4 Steady state sinusoidal wave conduction loss – double side cooled



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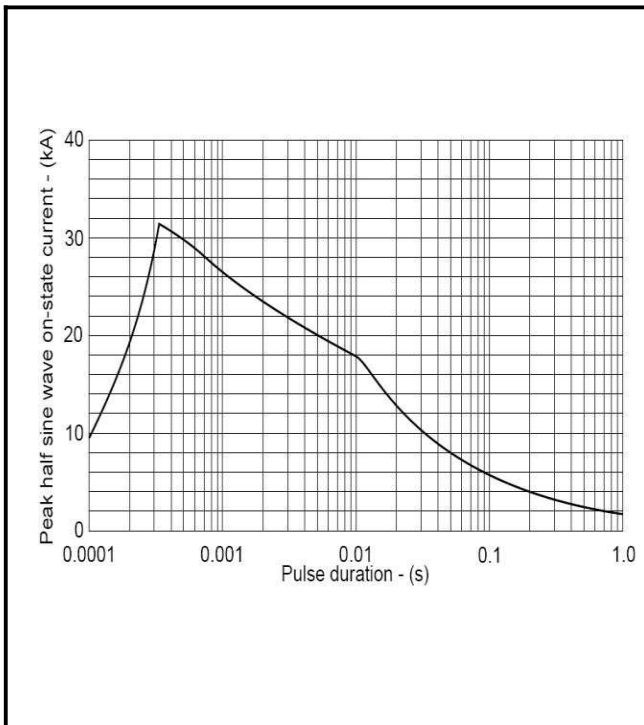


Fig.5 Surge (non-repetitive) on-state current vs time

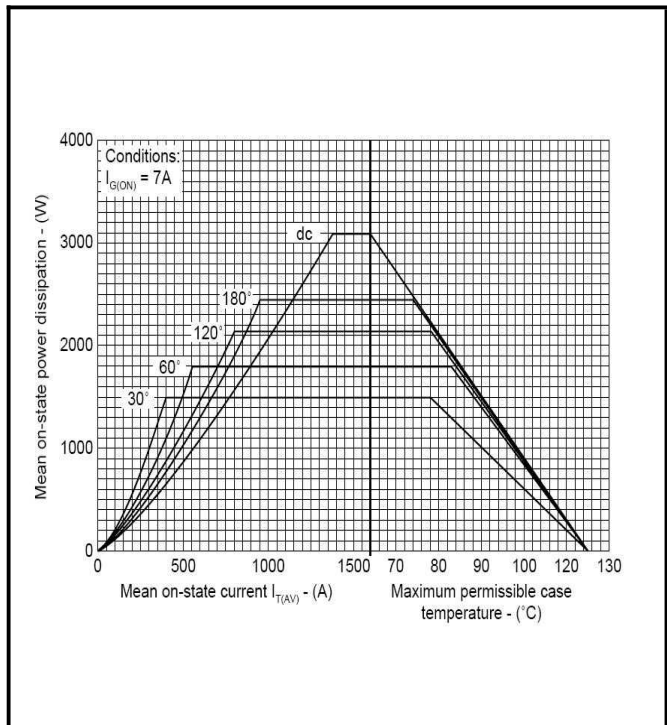


Fig.6 Steady state rectangular wave conduction loss – double side cooled

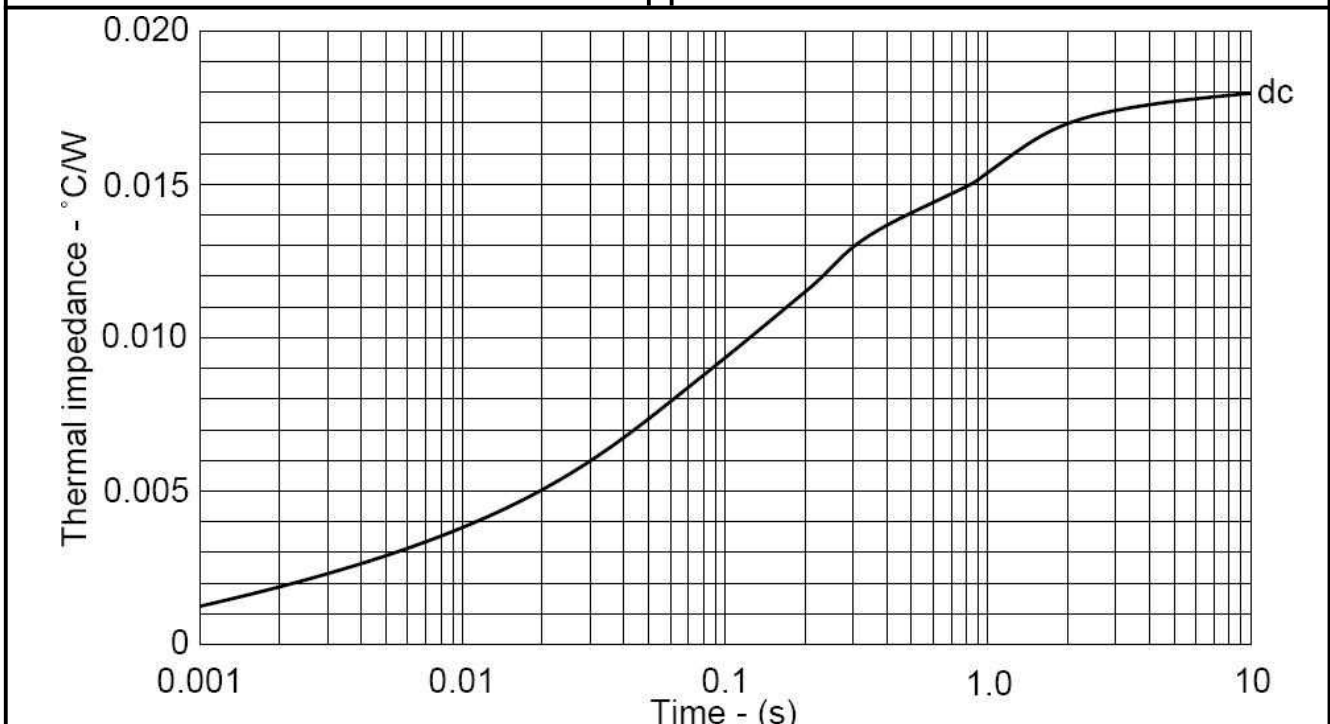


Fig.7 Maximum (limit) transient thermal impedance – junction to case (°C/kW)





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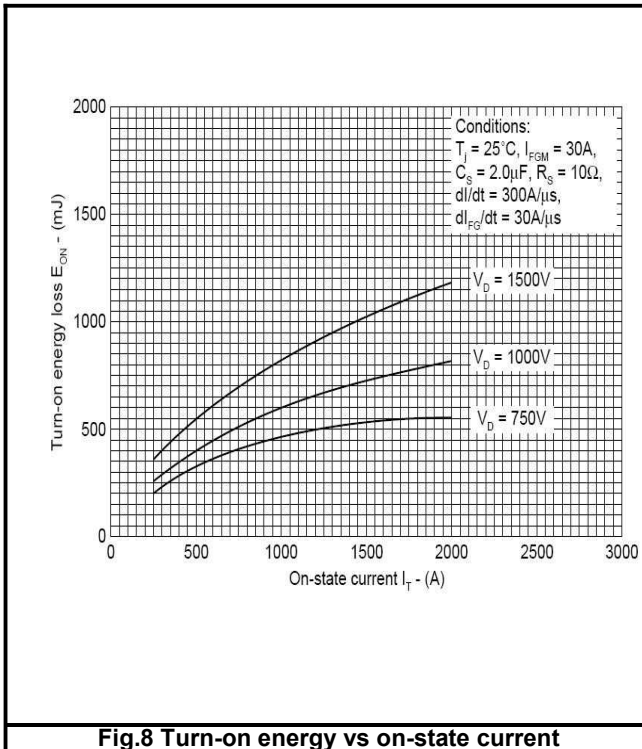


Fig.8 Turn-on energy vs on-state current

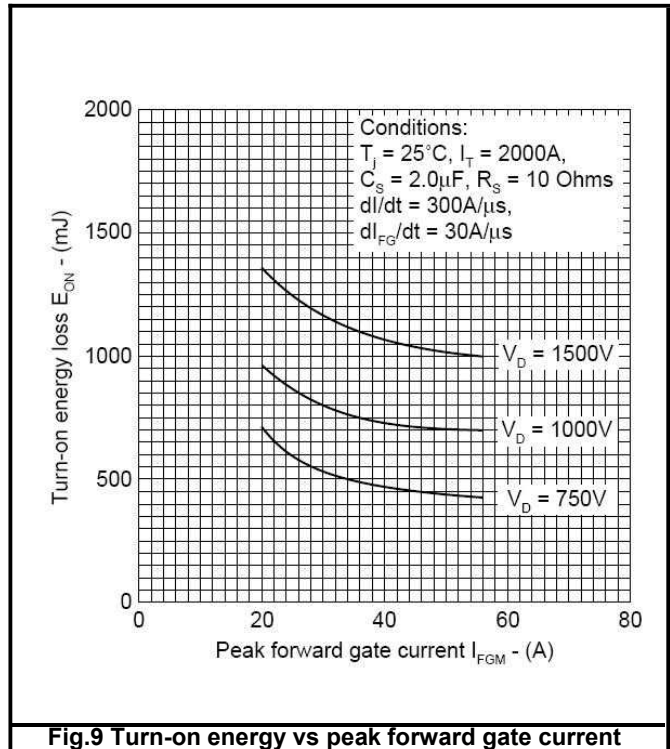


Fig.9 Turn-on energy vs peak forward gate current

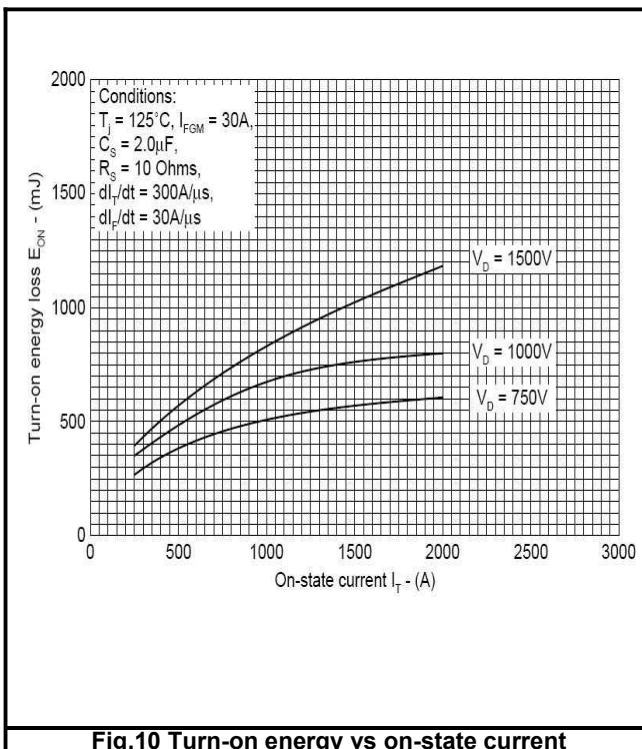


Fig.10 Turn-on energy vs on-state current

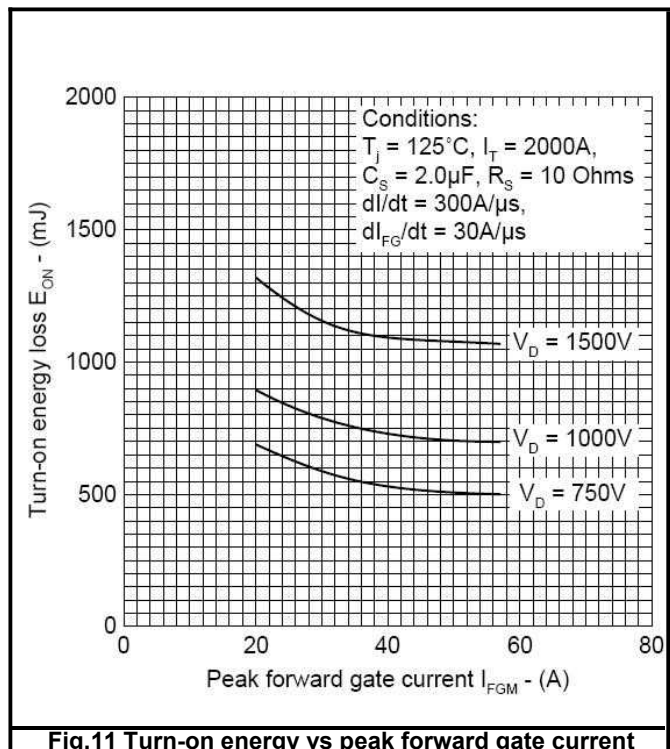


Fig.11 Turn-on energy vs peak forward gate current



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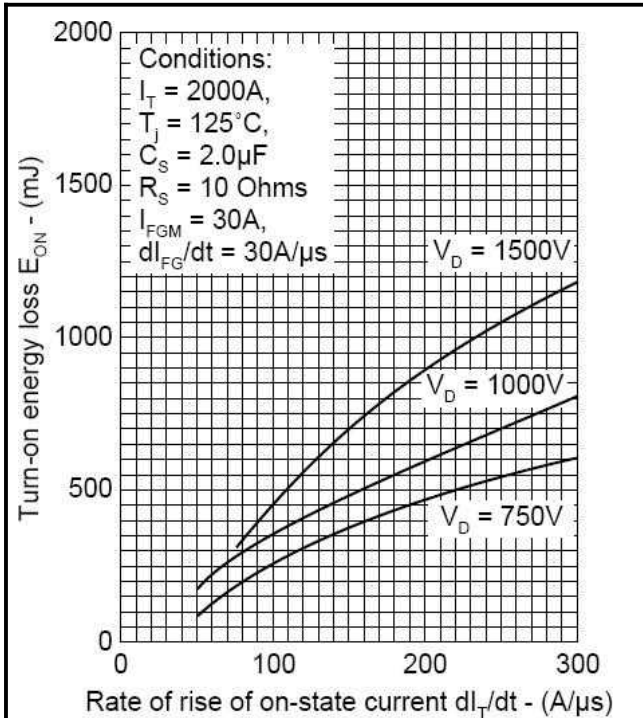


Fig.12 Turn-on energy vs rate of rise of on-state current

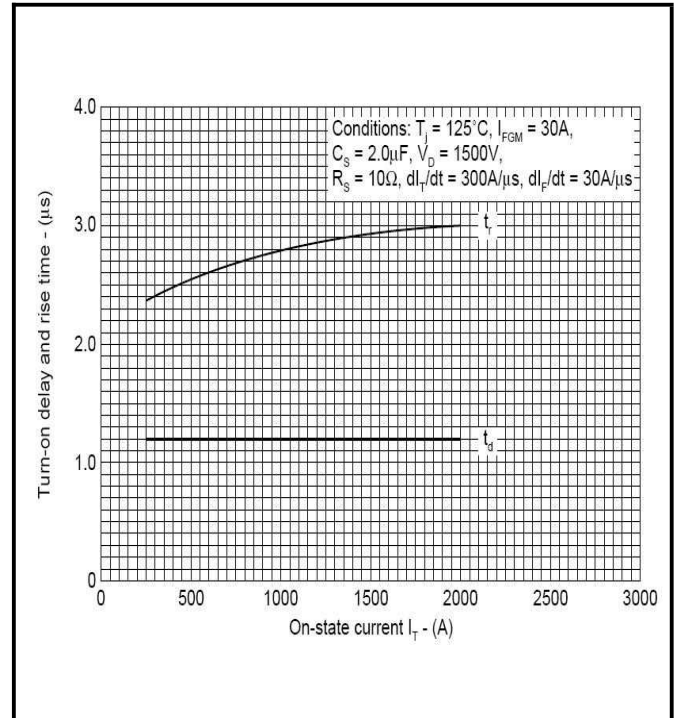


Fig.13 Delay time & rise time vs turn-on current

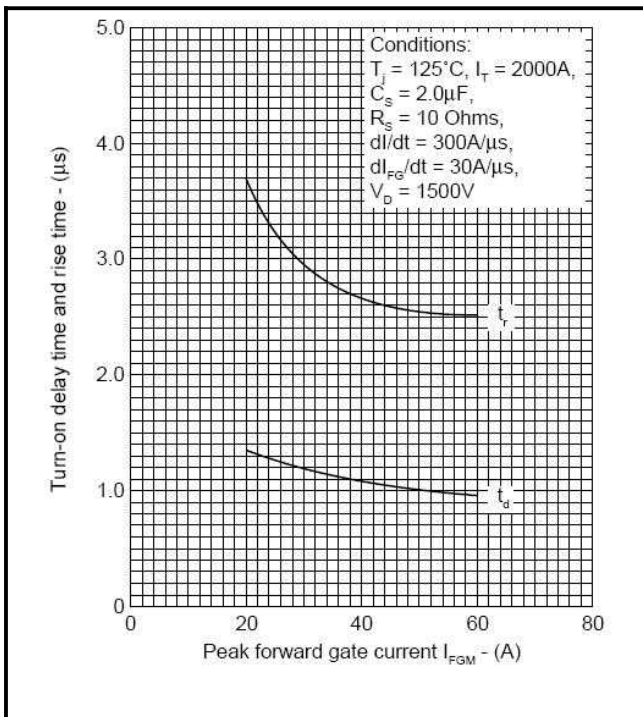


Fig.14 Delay time & rise time vs peak forward gate current

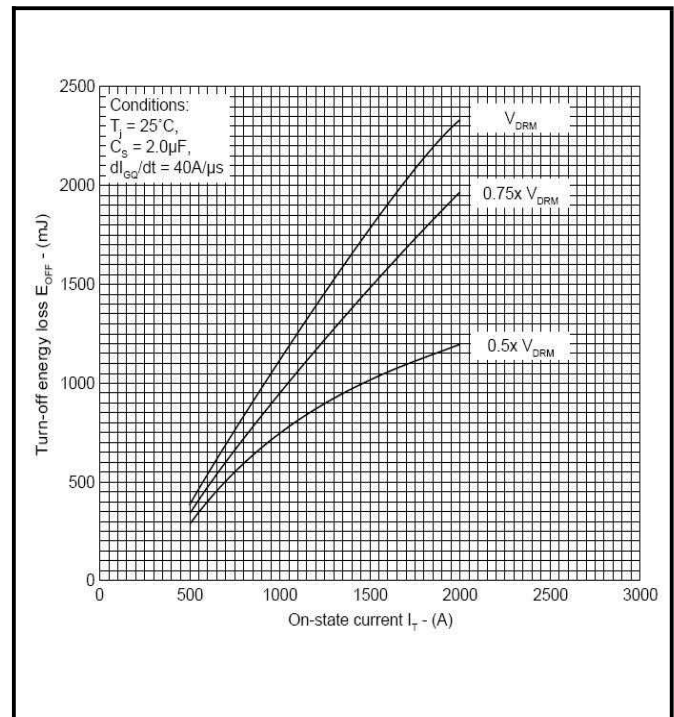


Fig.15 Turn-off energy vs on-state current





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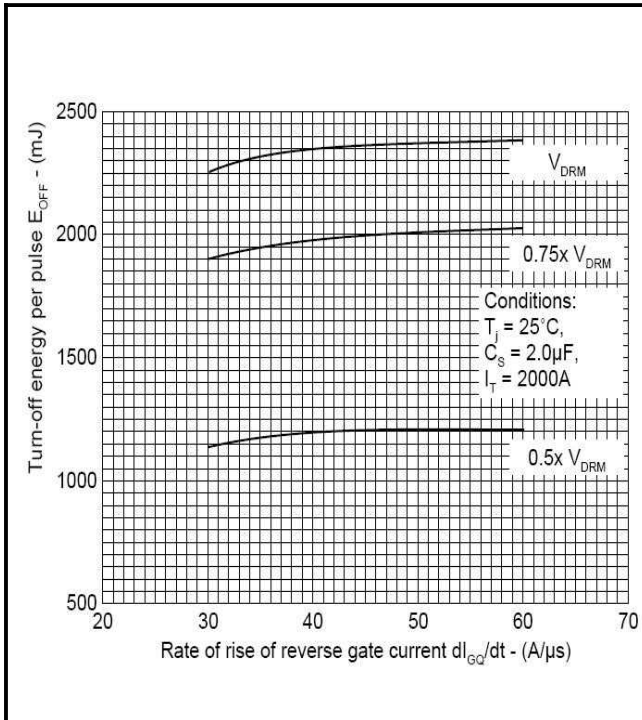


Fig.16 Turn-off energy vs rate of rise of reverse gate current

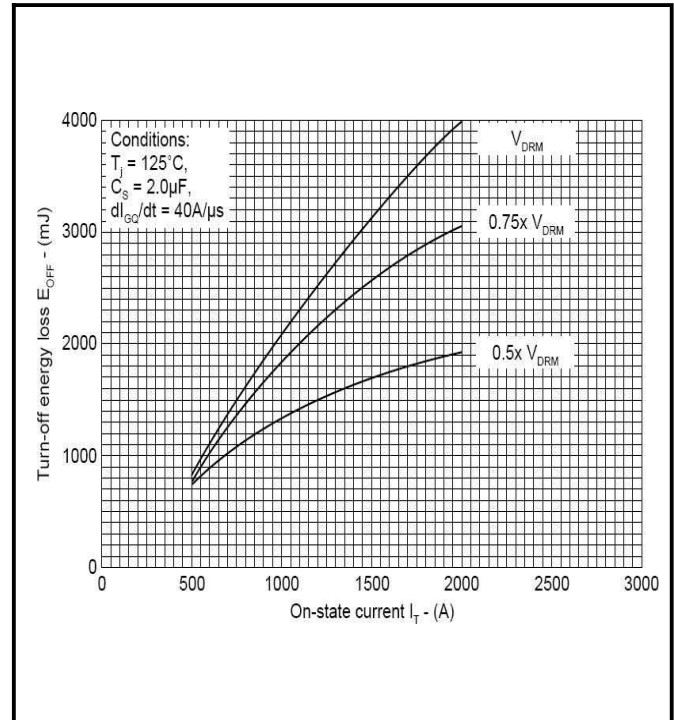


Fig.17 Turn-off energy vs on-state current

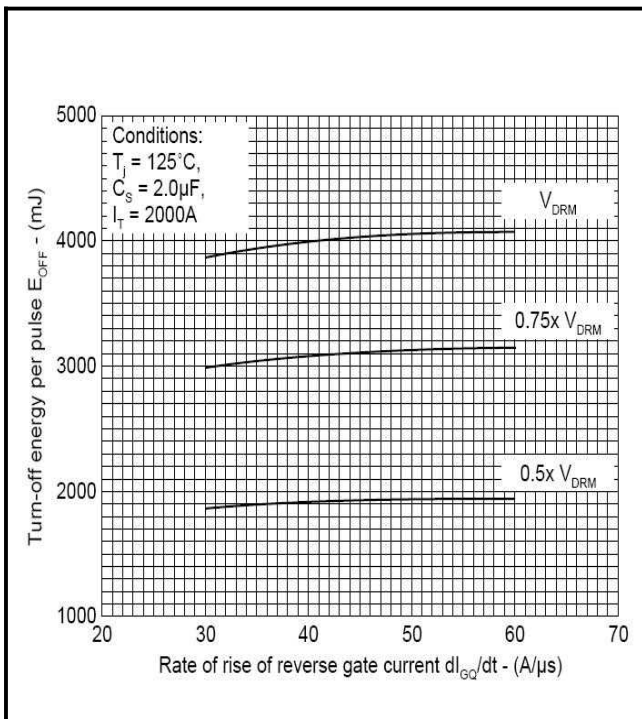


Fig.18 Turn-off energy vs rate of rise of reverse gate current

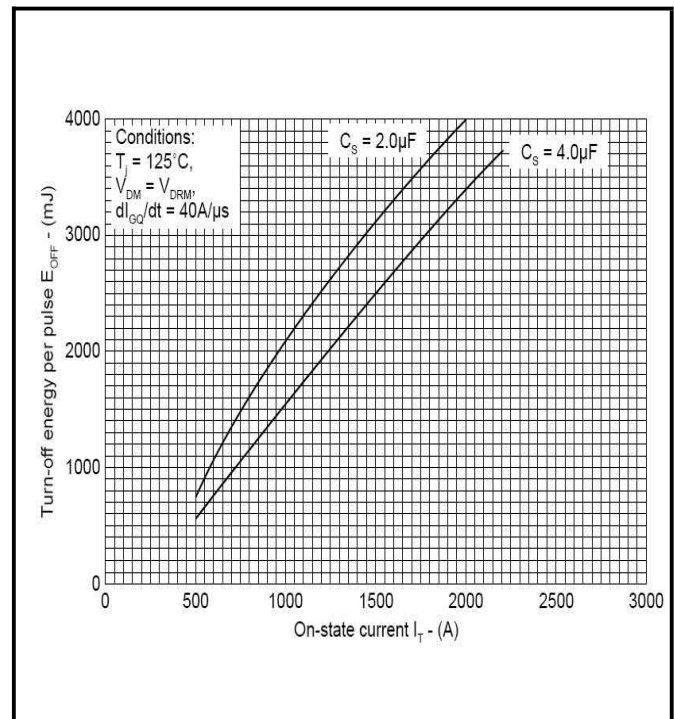
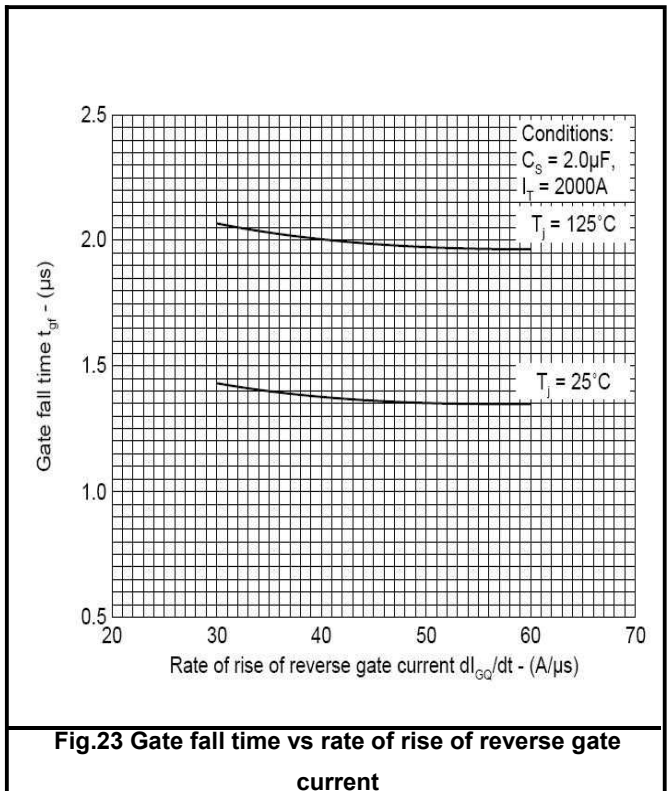
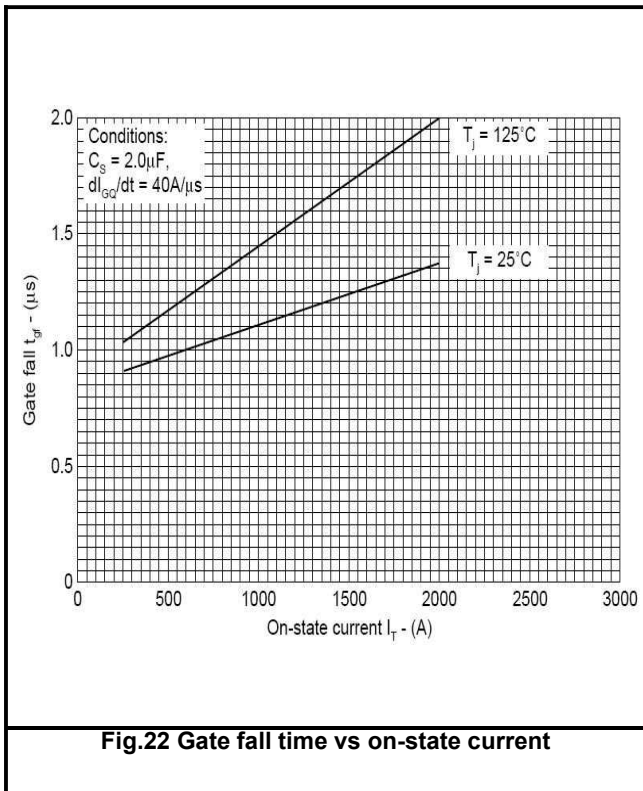
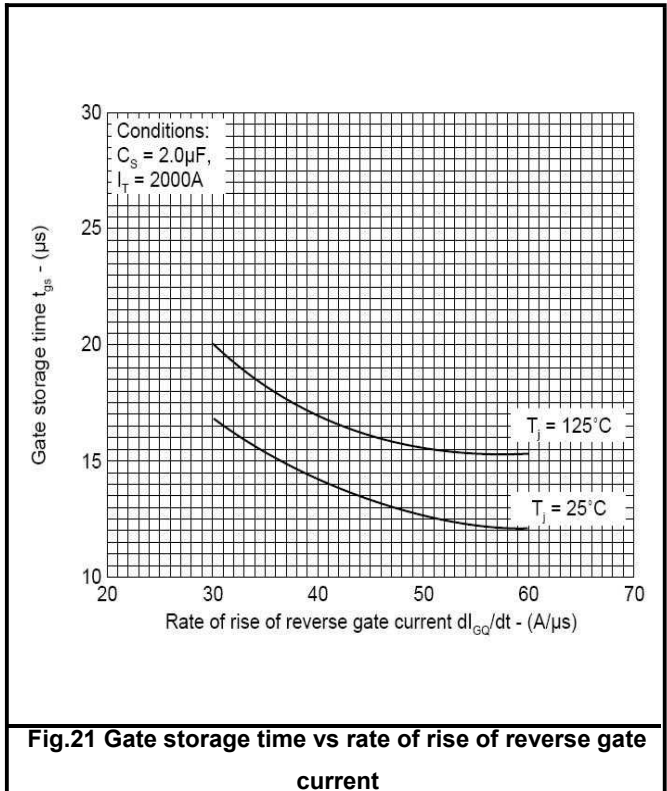
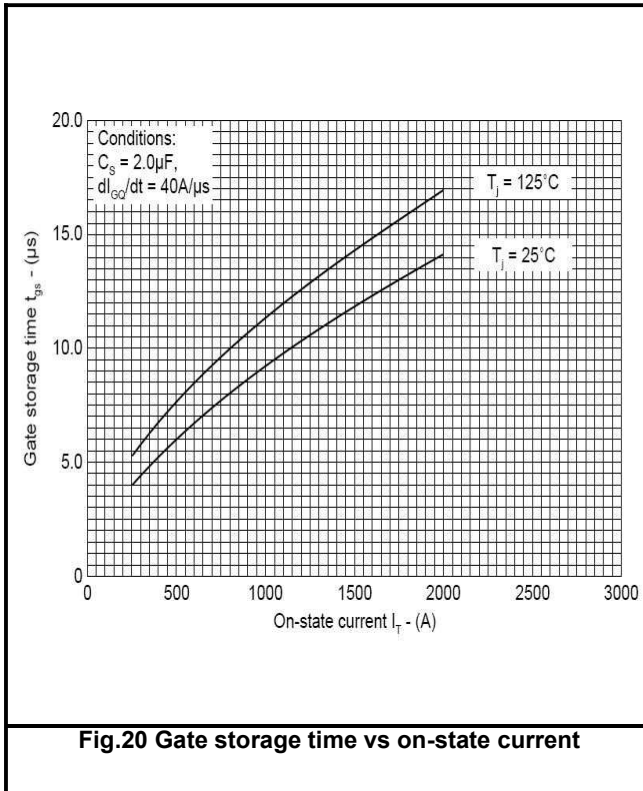


Fig.19 Turn-off energy vs on-state current





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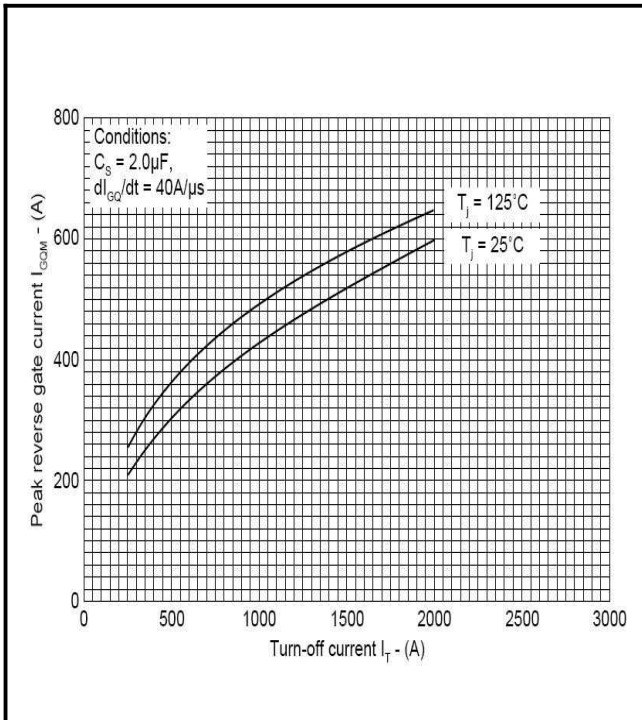


Fig.24 Peak reverse gate current vs turn-off current

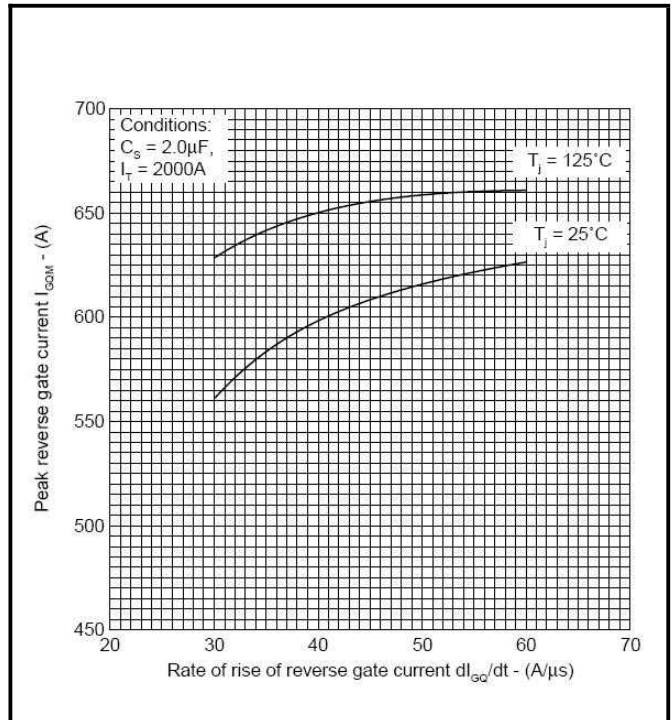


Fig.25 Peak reverse gate current vs rate of rise of reverse gate current

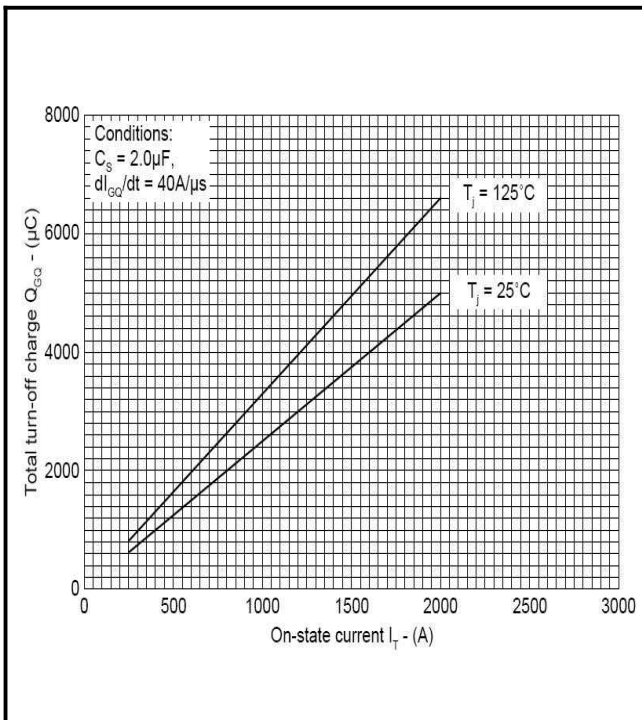


Fig.26 Turn-off gate charge vs on-state current

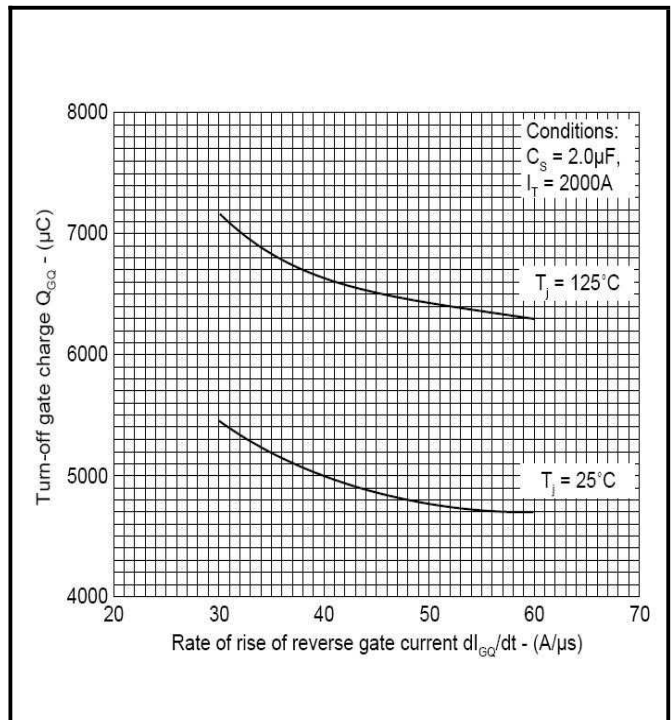


Fig.27 Turn-off gate charge vs rate of rise of reverse gate current



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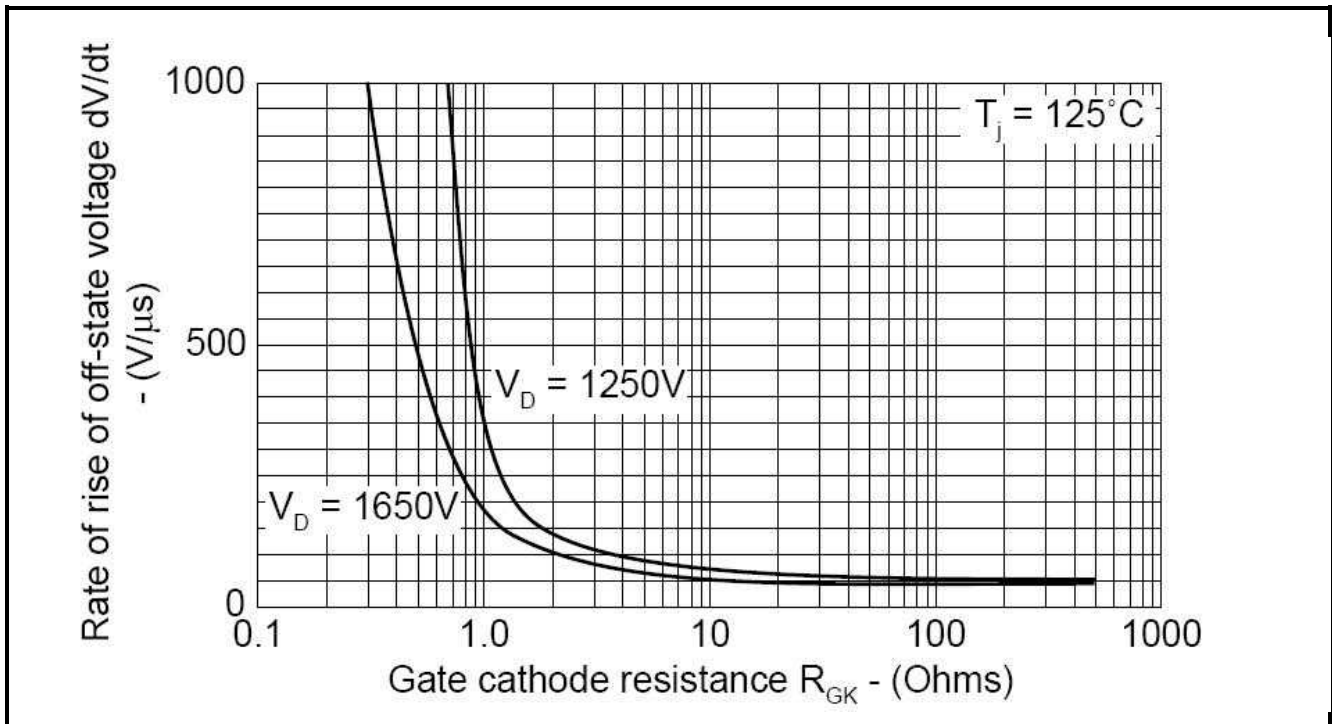
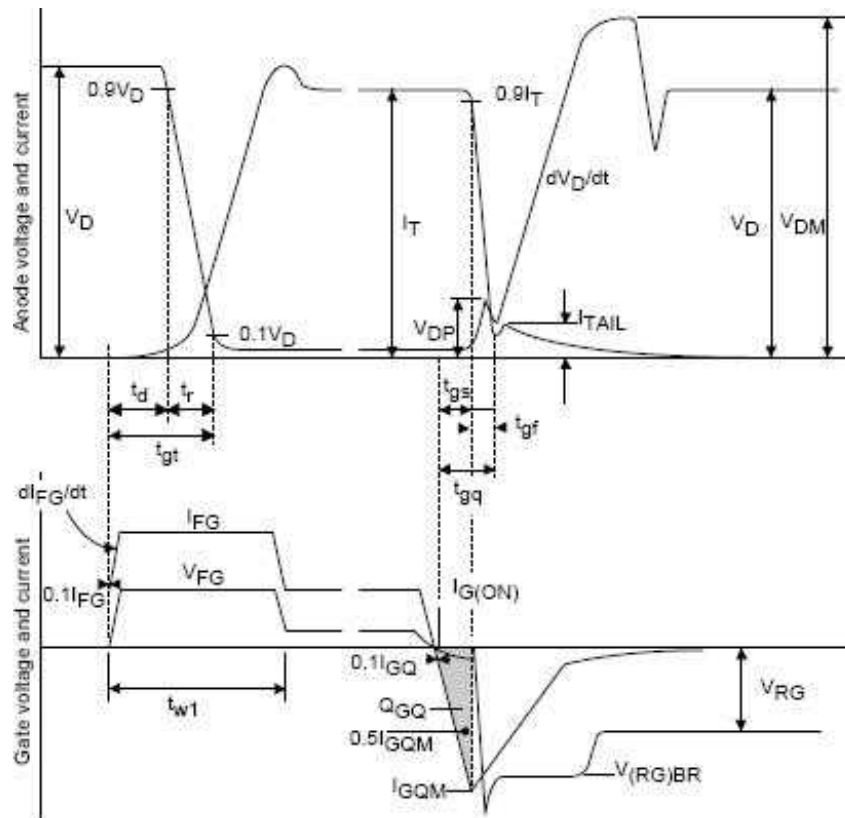


Fig.28 Rate of rise of off-state voltage vs gate cathode resistance



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Recommended gate conditions:  
 $I_{TCM} = 2000A$   
 $I_{FG} = 30A$   
 $I_{G(ON)} = 7A \text{ d.c.}$   
 $t_{w1(min)} = 20\mu s$   
 $I_{GQM} = 650 A$   
 $di_{GQ}/dt = 40A/\mu s$   
 $Q_{GQ} = 6600\mu C$   
 $V_{RG(min)} = 2V$   
 $V_{RG(max)} = 16V$

Fig.29 General switching waveforms





PACKAGE DETAILS

All dimensions in mm, unless stated otherwise. DO NOT SCALE.

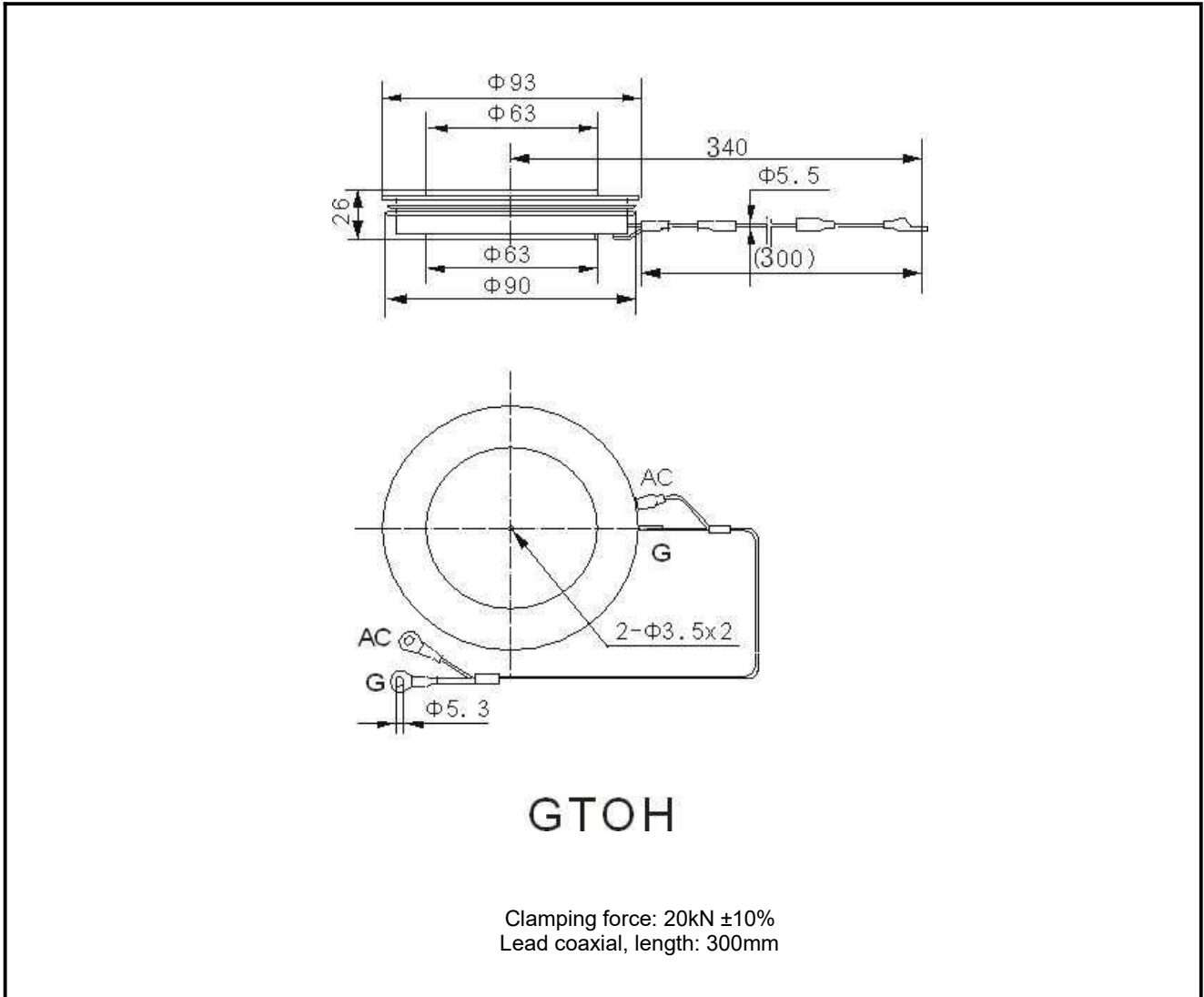


Fig.30 Package outline